Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
			* : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-05-19
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Laurent TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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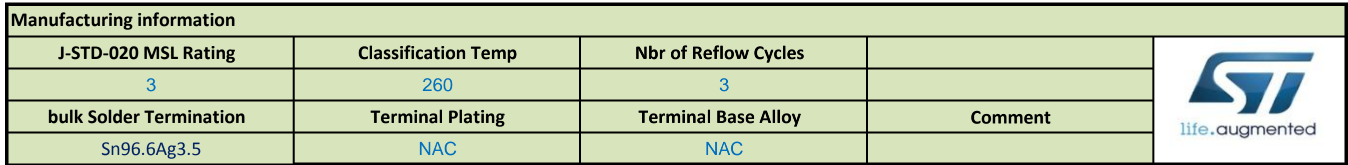
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L162VCH6	Y4MJ*427XXXX	A	9993	2014-04-28
	Amount	UoM	Unit type	ST ECOPACK Grade
	69,50	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Sn96.6Ag3.5	NAC	NAC		

Package Designator	Size	Nbr of instances	Shape	
BGA	7x7x0.6	100	No lead	
Comment	UFBGA 7x7x0.60 100L R12sq P0.5			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-16th December 2013	
Query	**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	Y4MJ*427XXXX					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
die (s)	Other inorganic materials	2,798	mg	supplier	die	Silicon (Si)	7440-21-3		2,394	mg	855611	34446
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0,033	mg	11794	475
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0,144	mg	51465	2072
die (s)				supplier	metallization	Tantalum (Ta)	7440-25-7		0,004	mg	1430	58
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0,015	mg	5361	216
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0,001	mg	357	14
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0,029	mg	10365	417
die (s)				supplier	passivation	Indium Tin oxide (In203:SnO2)	50926-11-9		0,178	mg	63617	2561
Die attach	Other inorganic materials	0,787	mg	supplier	Glue	Resins	na		0,354	mg	449809	5094
Die attach				supplier	Glue	Phenol-formaldehyde polymer	9003-35-4		0,079	mg	100381	1137
Die attach				supplier	Glue	Silica	67762-90-7		0,016	mg	20330	230
Die attach				supplier	Glue	Proprietary Material	na		0,338	mg	429479	4863
Substrate	Other inorganic materials	33,438	mg	supplier	Core	BIS(3-ETHYL-5-METHYL-4-MALEIMIDOPHENYL	105391-33-1		1,848	mg	55266	26590
Substrate				supplier	Core	Triazine	1156-51-0		1,848	mg	55266	26590
Substrate				supplier	Core	Phenolic Polymer Resin, Epikote 155	9003-36-5		1,848	mg	55266	26590
Substrate				supplier	Core	Aluminium hydroxide	21645-51-2		2,772	mg	82900	39885
Substrate				supplier	Core	Other inorganic filler	NA		2,772	mg	82900	39885
Substrate				supplier	Core	Glass fiber	65997-17-3		9,072	mg	271308	130532
Substrate				supplier	Solder mask	Proprietary Material-Cured resin	Trade secret		2,959	mg	88492	42576
Substrate				supplier	Solder mask	Barium sulfate	7727-43-7		1,494	mg	44680	21496
Substrate				supplier	Solder mask	Talc (Mg3H2(SiO3)4)	14807-96-6		0,173	mg	5174	2489
Substrate				supplier	Solder mask	Copper phthalocyanine bule	147-14-8		0,010	mg	299	144
Substrate				supplier	Solder mask	Silicon dioxide (SiO2)	7631-86-9		0,043	mg	1286	619
Substrate				supplier	Solder mask	Other aluminium compounds	Trade secret		0,010	mg	299	144
Substrate				supplier	Solder mask	Other miscellaneous substances	Trade secret		0,115	mg	3439	1655
Substrate				supplier	Cu foil	Copper (cu)	7440-50-8		5,541	mg	165710	79727
Substrate				supplier	Ni/Au plating	Nickel (Ni)	7440-02-0		2,554	mg	76380	36748
Substrate				supplier	Ni/Au plating	Gold (Au)	7440-57-5		0,379	mg	11334	5453
Encapsulation	Other inorganic materials	28,676	mg	supplier	Mold Compound	Silica, vitreous [Fused Silica]	60676-86-0		25,387	mg	885305	365281
Encapsulation				supplier	Encapsulation	Epoxy resins	na		1,144	mg	39894	16460
Encapsulation				supplier	Encapsulation	Phenolic resins	na		0,858	mg	29920	12345
Encapsulation				supplier	Encapsulation	Carbon black	1333-86-4		0,143	mg	4987	2058
Encapsulation				supplier	Encapsulation	Metal Hydroxide	na		0,858	mg	29920	12345
Encapsulation				supplier	Encapsulation	Other miscellaneous substances	na		0,286	mg	9973	4115
Bonding wire	Other inorganic materials	0,700	mg	supplier	Metals	Gold (Au)	7440-57-5		0,700	mg	1000000	10072
Solderball	Other inorganic materials	3,101	mg	supplier	Solder	Tin (Sn)	7440-31-5		2,992	mg	964850	43050
Solderball				supplier	Solder	Silver (Ag)	7440-22-4		0,109	mg	35150	1568